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(54) **PROBE HAVING A FRAME TO ALIGN SPRING PINS PERPENDICULARLY TO A PRINTED CIRCUIT BOARD, AND METHOD OF MAKING SAME**

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(57) **ABSTRACT**

(52) **U.S. Cl.** **324/754; 324/758; 324/761**

In one embodiment, a probe for probing test points on a target board includes a printed circuit board, a frame, and a plurality of spring pins. The printed circuit board (PCB) has a first side with a plurality of solder pads thereon, and a plurality of signal routes that are electrically coupled to the solder pads for routing signals to a test instrument. The frame is mechanically coupled to the PCB and has a main body portion with a plurality of holes therein. The holes in the frame are aligned with the plurality of solder pads on the first side of the PCB. The plurality of spring pins are provided for probing the test points on the target board, with each spring pin being i) disposed in one of the holes in the frame, perpendicularly abutting the first side of the PCB, and ii) electrically coupled to one of the solder pads. Other embodiments, including a method of making a probe, are also disclosed.

(58) **Field of Classification Search** None
See application file for complete search history.

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11 Claims, 7 Drawing Sheets

